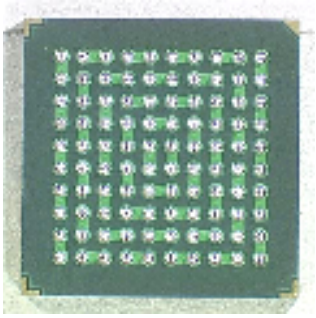
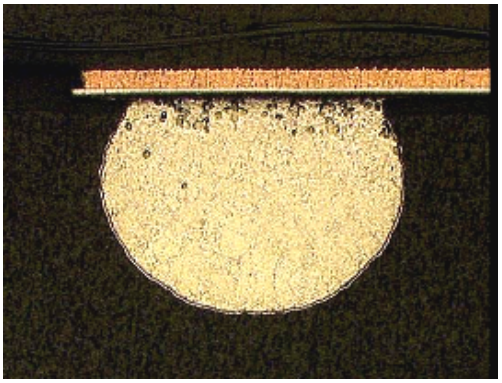
Package Characteristics: CABGA Sn63

Top View

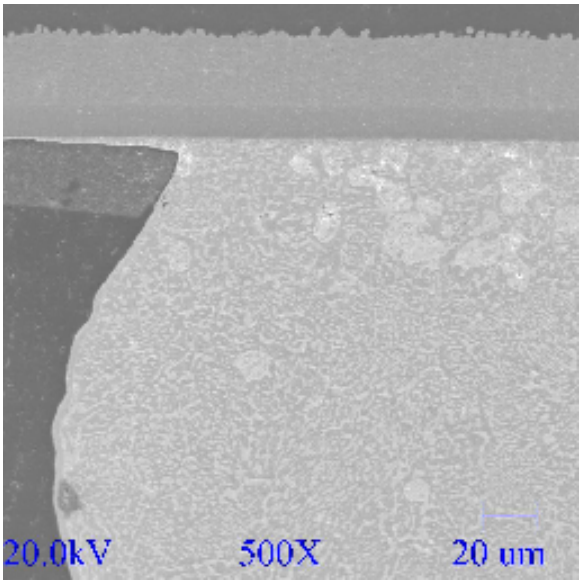


Bottom View

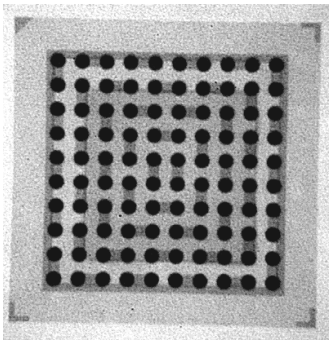
Feature	Value
Package Length	10.01 mm
Package Width	10.01 mm
Package Thickness	0.99 mm
Solder ball diameter	0.471 mm
Die Length	5.5 mm
Die Width	5.55 mm
Die Thickness	0.26 mm
Pitch	0.80 mm
Weight	0.2458 g
CTE	8.329 ppm/C
Width of Solder ball in contact with component pad	0.399 mm
Solderball Alloy (SEM estimation)	Sn63Pb37



Cross-section of solder ball



SEM of solder ball x-section



X-ray